

YTV B3 AOI

Benchtop Automated Optical Inspection

- Quick Set-up
- Mega-pixel Color Camera
- High Defect Coverage
- Low False Failure Rate
- Best Price Performance



YESTech's advanced Thin Camera™ technology offers off-line benchtop PCB inspection with exceptional defect coverage. This benchtop system inspects solder joints and verifies correct part assembly enabling users to improve quality and increase throughput.

Programming the B3 is fast and intuitive. Operators typically take less than 30 minutes to create a complete inspection program including solder inspection. The B3 utilizes a standard package library to simplify training and insure program portability across manufacturing lines. Programs created with the B3 are also compatible with YESTech's complete line of AOI systems.

Newly available Fusion Lighting™ and advanced image processing technology integrates several techniques, including color, normalized correlation and rule-base algorithms, to provide complete inspection coverage with an extremely low false failure rate.

The B3 is equally effective for pre / post-reflow or even final assembly inspection. Remote programming maximizes machine utilization and real-time SPC monitoring provides a valuable yield enhancement solution.

Automated Inspection for:

- Solder & lead defects
- Component presence and position
- Correct part
- Polarity
- Through-hole parts
- Paste

Inspection Capabilities

Throughput:	4 sq. in./ sec.: > 200,000 components per hour
Maximum Board Size:	18" x 20" (457mm x 508mm)
Clearance:	2" (50mm) top and bottom
Minimum Component Size:	01005
Defects Detected:	Component: position, missing, wrong, polarity, skew, tombstone Lead: bent, lifted, bridging Solder: open, insufficient, short, solder balls

Software

Algorithms:	Normalized correlation, OCV, OCR, barcode recognition and rule-based
Data Requirements:	Gerber Data, ASCII Text, Most Native CAD Formats
CAD Translation Package:	CircuitCAM, Unicam, YESTech CAD Utility
Programming Skill Level:	Technician or operator
Operating System:	Windows XP
Off-line Software:	Optional - Rework, Review and Program Creation
SPC Software:	Optional - Real-time local and remote monitoring of first pass yield, defect trends, and machine utilization.

Hardware

Lighting:	Proprietary Fusion Lighting™ multiangle LED
Imager:	Thin Camera: 25 micron, and / or 12 micron pixel size Resolution 1280 x 1024

Facilities

Power:	110-220 VAC, 50/60 Hz, 10 amps
Footprint:	34" x 39" x 17" (864mm x 991mm x 432mm)
Weight:	170 lbs (77 kg)
Machine Installation:	< 1 hour

